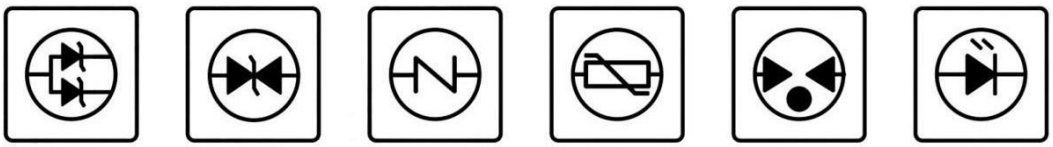
MSKSEMI 美森科
SEMICONDUCTOR



P0300FA-MS

Product specification

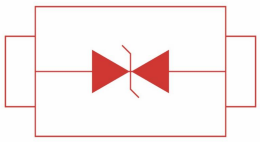
Features

- Low capatcitance
- Cannot be damaged by voltage
- Will not fatigue
- Eliminate voltage overshoot
- Glass passivated junction
- Halogen free and RoHS compliant

Mechanical Data

- CASE: SMF(SOD-123FL) Molded Plastic
- UL Flammability Classification Rating 94V0
- Mounting Position:Any

Reference News

PACKAGE OUTLINE	Pin Configuration	Marking
 SOD-123FL		P03F

Maximum Ratings & Thermal Characteristics

(Ratings at 25℃ ambient temperature unless otherwise specified.)

Parameter	Symbol	Value	Units	Remarks
Peak Pulse Voltage	V_{PP}	1800	V	10/700us
Peak Pulse Current	I_{PP}	40	A	10/1000us
Peak Pulse Current	I_{PK}	150	A	8/20us
Peak One-cycle Surge Current	I_{TSM}	20	A	60Hz
Rate of Rise of Current	di/dt	500	A/us	
Typical Thermal Resistance Junction to Lead	$R_{\theta JL}$	30	℃/W	
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	120	℃/W	
Operating Temperature Range	T_J	-40 to 150	℃	
Storage Temperature Range	T_{STG}	-55 to 150	℃	

Electrical Characteristics

(Ratings at 25 ℃ ambient temperature unless otherwise specified).

Part Number	V_S @100KV/S V MAX	I_{S_LMT} mA	V_T @ I_T V MAX	I_T A	I_D @ V_D uA MAX	V_D V	C_O@1MHz,2V_{DC} pF TYP	I_H mA MIN
P0300FA-MS	25	500	4	2.2	5	15	35	30

Ratings and Characteristic Curves

（Ratings at 25℃ ambient temperature unless otherwise specified).

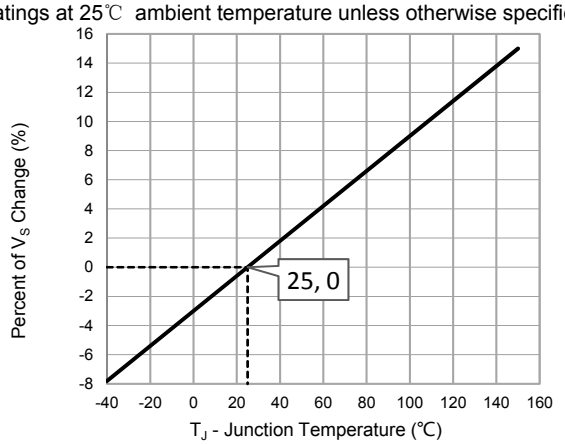


Fig.1 - Peak Pulse Current Rating

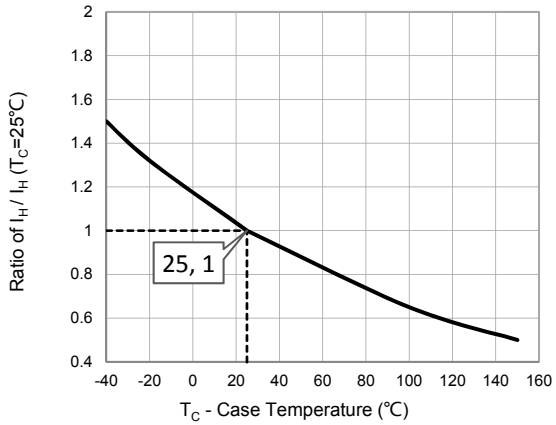


Fig.2 - Normalized DC Holding Current vs. Case Temperature

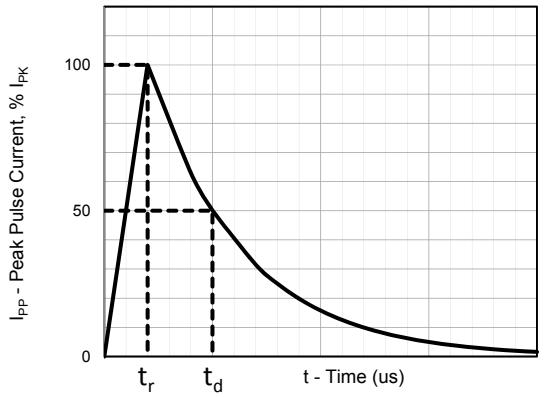


Fig.3 - tr/td us Pulse Waveform

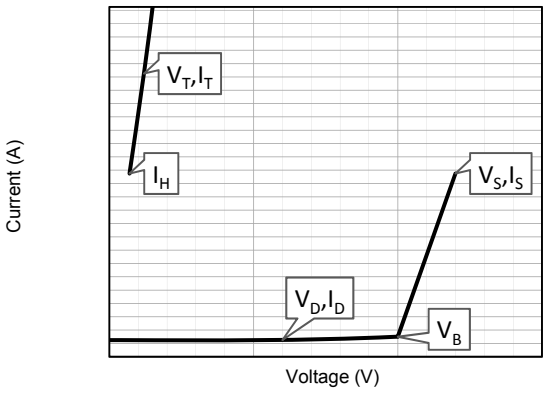


Fig.4 - VI Curve

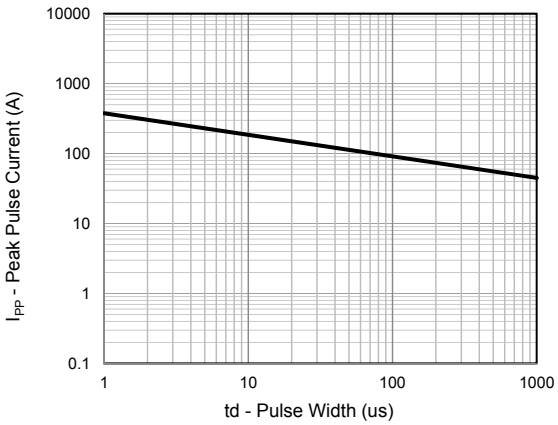


Fig.5 - Peak Pulse Current Rating

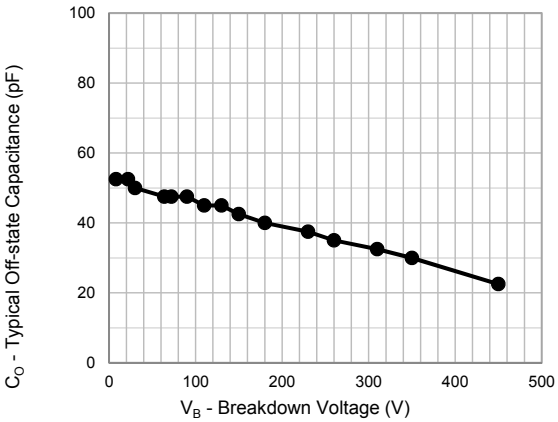
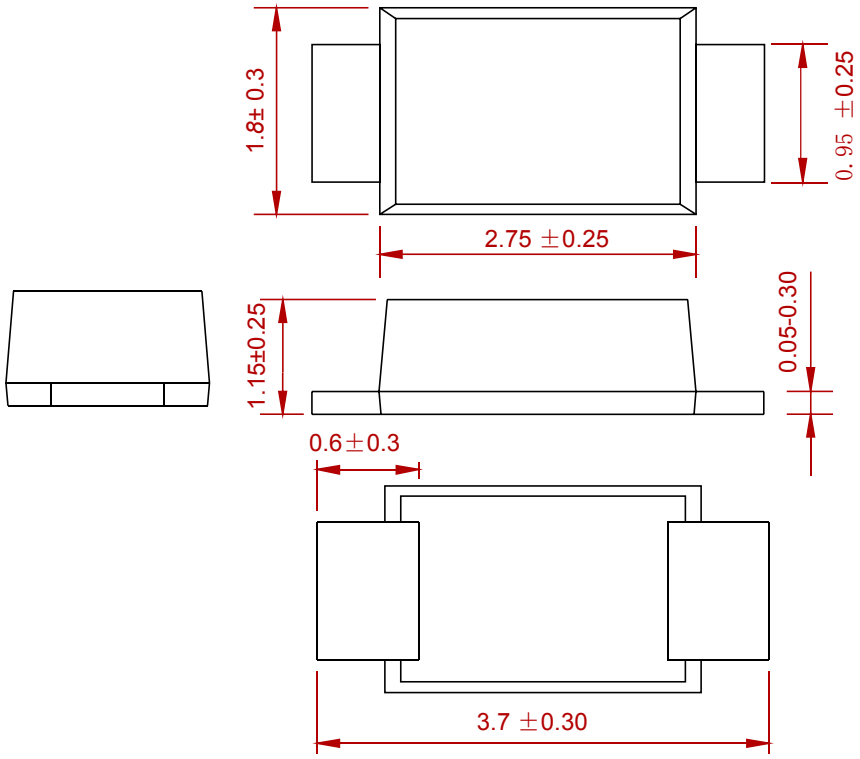


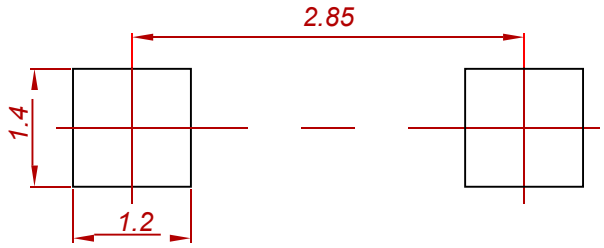
Fig.6 - Typical Off-state Capacitance

PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
P0300FA-MS	SOD-123FL	3000

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